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Tender

Supply, Delivery and Installation of wafer dicing kit for NMIS

University of Strathclyde

F02: Contract notice

Notice identifier: 2024/S 000-018851

Procurement identifier (OCID): ocds-h6vhtk-047100

Published 19 June 2024, 10:22am

Section I: Contracting authority

I.1) Name and addresses

University of Strathclyde

McCance Building, 16 Richmond Street

Glasgow

G1 1XQ

Email

jen.robertson@strath.ac.uk

Telephone

+44 7811592949

Country

United Kingdom

NUTS code

UKM82 - Glasgow City

Internet address(es)

Main address

http://www.strath.ac.uk/

Buyer's address

https://www.publiccontractsscotland.gov.uk/search/Search_AuthProfile.aspx?ID=AA0011 3

I.2) Information about joint procurement

The contract is awarded by a central purchasing body

I.3) Communication

The procurement documents are available for unrestricted and full direct access, free of charge, at

https://www.publictendersscotland.publiccontractsscotland.gov.uk/esop/pts-host/public/pts/web/login.html

Additional information can be obtained from the above-mentioned address

Tenders or requests to participate must be submitted electronically via

https://www.publictendersscotland.publiccontractsscotland.gov.uk/esop/toolkit/dashboard/dashboard.do? ncp=1718717323289.17229-1

Electronic communication requires the use of tools and devices that are not generally available. Unrestricted and full direct access to these tools and devices is possible, free of charge, at

https://www.publictendersscotland.publiccontractsscotland.gov.uk/esop/toolkit/dashboard/dashboard.do?_ncp=1718717323289.17229-1

I.4) Type of the contracting authority

Body governed by public law

I.5) Main activity

Education

Section II: Object

II.1) Scope of the procurement

II.1.1) Title

Supply, Delivery and Installation of wafer dicing kit for NMIS

Reference number

UOS-30411-2024

II.1.2) Main CPV code

• 31712330 - Semiconductors

II.1.3) Type of contract

Supplies

II.1.4) Short description

The National Manufacturing Institute Scotland is in the process of expanding its manufacturing capability into the semiconductor advanced packaging area with specific focus on power electronic semiconductors. To support this expansion, NMIS intends to procure equipment that can support a wide variety of power electronic semiconductor designs and packaging requirements. The concept design for the facility will support a publicly funded project which will see the creation of an advanced facility for developing and scaling-up packaging capabilities and includes provision of equipment that is sufficiently flexible to support a wide variety of power electronic semiconductor design and packaging requirements.

II.1.5) Estimated total value

Value excluding VAT: £1,000,000

II.1.6) Information about lots

This contract is divided into lots: Yes

Tenders may be submitted for all lots

II.2) Description

II.2.1) Title

Saw Dicing

Lot No

1

II.2.2) Additional CPV code(s)

• 31712330 - Semiconductors

II.2.3) Place of performance

NUTS codes

• UKM82 - Glasgow City

Main site or place of performance

University of Strathclyde

II.2.4) Description of the procurement

The National Manufacturing Institute Scotland is in the process of expanding its manufacturing capability into the semiconductor advanced packaging area with specific focus on power electronic semiconductors. To support this expansion, NMIS intends to procure equipment that can support a wide variety of power electronic semiconductor designs and packaging requirements. The concept design for the facility will support a publicly funded project which will see the creation of an advanced facility for developing and scaling-up packaging capabilities and includes provision of equipment that is sufficiently flexible to support a wide variety of power electronic semiconductor design and packaging requirements.

The overall scale up manufacturing facility is to be housed at an NMIS site, this subsection of the facility will be housed in a ISO-7 (previously class 10,000) clean room environment. The equipment will comprise the latest technology in their respective fields. It will be utilized in a range of projects within the Power Electronics industry and will be made available to both academic and industrial partners across the whole of the United Kingdom, including other catapult centres.

The facility will have capability to prepare, dice/cut, bond, interconnect, package, and test semiconductor products that are part of the power electronics sector. These stages will be carried out across dedicated research and development cells.

The University is seeking to establish a contract for wafer dicing equipment and is subsequently tendering the lots outlined below:

Lot 1 – Saw Dicing

II.2.5) Award criteria

Quality criterion - Name: quality / Weighting: 50

Price - Weighting: 50

II.2.7) Duration of the contract, framework agreement or dynamic purchasing system

Duration in months

18

This contract is subject to renewal

No

II.2.10) Information about variants

Variants will be accepted: No

II.2.11) Information about options

Options: Yes

Description of options

The Contracting Authority reserves the right to request additional deliveries by the Successful Tenderer, either intended as partial replacement of suppliers or installations or as extensions of existing supplies and installations.

II.2.13) Information about European Union Funds

The procurement is related to a project and/or programme financed by European Union funds: No

II.2) Description

II.2.1) Title

Laser Dicing

Lot No

2

II.2.2) Additional CPV code(s)

• 31712330 - Semiconductors

II.2.3) Place of performance

NUTS codes

• UKM82 - Glasgow City

II.2.4) Description of the procurement

The National Manufacturing Institute Scotland is in the process of expanding its manufacturing capability into the semiconductor advanced packaging area with specific focus on power electronic semiconductors. To support this expansion, NMIS intends to procure equipment that can support a wide variety of power electronic semiconductor designs and packaging requirements. The concept design for the facility will support a publicly funded project which will see the creation of an advanced facility for developing and scaling-up packaging capabilities and includes provision of equipment that is sufficiently flexible to support a wide variety of power electronic semiconductor design and packaging requirements.

The overall scale up manufacturing facility is to be housed at an NMIS site, this subsection of the facility will be housed in a ISO-7 (previously class 10,000) clean room environment. The equipment will comprise the latest technology in their respective fields. It will be utilized in a range of projects within the Power Electronics industry and will be made available to both academic and industrial partners across the whole of the United Kingdom, including other catapult centres.

The facility will have capability to prepare, dice/cut, bond, interconnect, package, and test semiconductor products that are part of the power electronics sector. These stages will be carried out across dedicated research and development cells.

The University is seeking to establish a contract for wafer dicing equipment and is subsequently tendering the lots outlined below:

Lot 2 – Laser Dicing

II.2.5) Award criteria

Quality criterion - Name: quality / Weighting: 50

Price - Weighting: 50

II.2.7) Duration of the contract, framework agreement or dynamic purchasing system

Duration in months

18

This contract is subject to renewal

No

II.2.10) Information about variants

Variants will be accepted: No

II.2.11) Information about options

Options: Yes

Description of options

The Contracting Authority reserves the right to request additional deliveries by the Successful Tenderer, either intended as partial replacement of suppliers or installations or as extensions of existing supplies and installations.

II.2.13) Information about European Union Funds

The procurement is related to a project and/or programme financed by European Union funds: No

II.2) Description

II.2.1) Title

Scribe & Break

Lot No

3

II.2.2) Additional CPV code(s)

• 31712330 - Semiconductors

II.2.3) Place of performance

NUTS codes

• UKM82 - Glasgow City

II.2.4) Description of the procurement

The National Manufacturing Institute Scotland is in the process of expanding its manufacturing capability into the semiconductor advanced packaging area with specific focus on power electronic semiconductors. To support this expansion, NMIS intends to procure equipment that can support a wide variety of power electronic semiconductor designs and packaging requirements. The concept design for the facility will support a publicly funded project which will see the creation of an advanced facility for developing and scaling-up packaging capabilities and includes provision of equipment that is sufficiently flexible to support a wide variety of power electronic semiconductor design and packaging requirements.

The overall scale up manufacturing facility is to be housed at an NMIS site, this subsection of the facility will be housed in a ISO-7 (previously class 10,000) clean room environment. The equipment will comprise the latest technology in their respective fields. It will be utilized in a range of projects within the Power Electronics industry and will be made available to both academic and industrial partners across the whole of the United Kingdom, including other catapult centres.

The facility will have capability to prepare, dice/cut, bond, interconnect, package, and test semiconductor products that are part of the power electronics sector. These stages will be carried out across dedicated research and development cells.

The University is seeking to establish a contract for wafer dicing equipment and is subsequently tendering the lots outlined below:

Lot 3 – Scribe & Break

II.2.5) Award criteria

Quality criterion - Name: quality / Weighting: 50

Price - Weighting: 50

II.2.7) Duration of the contract, framework agreement or dynamic purchasing system

Duration in months

18

This contract is subject to renewal

No

II.2.10) Information about variants

Variants will be accepted: No

II.2.11) Information about options

Options: Yes

Description of options

The Contracting Authority reserves the right to request additional deliveries by the Successful Tenderer, either intended as partial replacement of suppliers or installations or as extensions of existing supplies and installations.

II.2.13) Information about European Union Funds

The procurement is related to a project and/or programme financed by European Union funds: No

Section III. Legal, economic, financial and technical information

III.1) Conditions for participation

III.1.2) Economic and financial standing

List and brief description of selection criteria

4B 1.2 Turnover

Bidders will be required to have the average yearly turnover to participate in the relevant lot (see below) This is to ensure the University is protected from any unforeseen financial risks that may impact the supplier or supply chain.

Lot 1 - GBP 600,000 for the last 3 (three) years

Lot 2 - GBP 2,000,000 for the last 3 (three) years

Lot 3 - GBP 1,600,000 for the last 3 (three) years

Minimum level(s) of standards possibly required

4B.5.1- 4B5.3 Insurances

Insurance requirements are in line with levels identified in the UOS standard Terms and Conditions.

It is a requirement of this contract that bidders can hold or commit to obtain prior to the commencement of any subsequently awarded contract, the types of insurance indicated below:

The Contractor shall maintain in force with reputable insurers

Employer's (Compulsory) Liability Insurance = GBP 10m

Public and Product Liability Insurance = GBP 10m

Professional Risk Indemnity Insurance = GBP 1m

In respect of any one incident and unlimited as to numbers of claims

III.1.3) Technical and professional ability

List and brief description of selection criteria

4C.1.2 Previous Experience

Bidders will be required to provide three (3) examples that demonstrate that they have the relevant experience to deliver the equipment as stated in the Contract Notice.

Section IV. Procedure

IV.1) Description

IV.1.1) Type of procedure

Open procedure

IV.1.8) Information about the Government Procurement Agreement (GPA)

The procurement is covered by the Government Procurement Agreement: Yes

IV.2) Administrative information

IV.2.2) Time limit for receipt of tenders or requests to participate

Date
22 July 2024
Local time
12:00pm
IV.2.4) Languages in which tenders or requests to participate may be submitted
English
IV.2.6) Minimum time frame during which the tenderer must maintain the tender
Duration in months: 4 (from the date stated for receipt of tender)
IV.2.7) Conditions for opening of tenders
Date
Date 22 July 2024
22 July 2024
22 July 2024 Local time
22 July 2024 Local time 12:00pm
22 July 2024 Local time 12:00pm Place

Section VI. Complementary information

VI.1) Information about recurrence

This is a recurrent procurement: No

VI.2) Information about electronic workflows

Electronic ordering will be used

Electronic invoicing will be accepted

Electronic payment will be used

VI.3) Additional information

The buyer is using PCS-Tender to conduct this ITT exercise. The Project code is 26821. For more information see:

http://www.publiccontractsscotland.gov.uk/info/InfoCentre.aspx?ID=2343

Community benefits are included in this requirement. For more information see: https://www.gov.scot/policies/public-sector-procurement/community-benefits-in-procurement/

A summary of the expected community benefits has been provided as follows:

Please see Procurement documents for full details

The buyer is using PCS-Tender to conduct this ITT exercise. The Project code is 26821. For more information see:

http://www.publiccontractsscotland.gov.uk/info/InfoCentre.aspx?ID=2343

Community benefits are included in this requirement. For more information see: https://www.gov.scot/policies/public-sector-procurement/community-benefits-in-procurement/

A summary of the expected community benefits has been provided as follows:

Community benefits are included in this requirement. For more information see: https://www.gov.scot/policies/public-sector-procurement/community-benefits-in-procurement/

A summary of the expected community benefits has been provided as follows:

Please see Procurement documents for full details

(SC Ref:769827)

VI.4) Procedures for review

VI.4.1) Review body

Glasgow Sheriff Court

Glasgow

Country

United Kingdom

VI.4.3) Review procedure

Precise information on deadline(s) for review procedures

An economic operator that suffers, or risks suffering, loss or damage attributable to a breach of duty under the Public Contracts (Scotland) Regulations

2015(SSI2015/446) (as amended) may bring proceedings in the Sheriff Court or the Court of Session.